



### **General Description**

The MAX14566E/MAX14566AE/MAX14566BE are second-generation USB devices that combine Hi-Speed USB analog switches with a USB host charger (dedicated charger) identification circuit. These devices support both the latest USB Battery Charging Specification Revision 1.2 including data contact detection and a set resistor bias for Apple-compliant devices as well as legacy USB D+/D-short detection using data line pullup. The MAX14566E has a pMOSFET open-drain control output (CEN) and the MAX14566AE has an nMOSFET open-drain control output (CEN) to restart the peripheral connected to the USB host.

These devices feature high-performance Hi-Speed USB switches with low 4pF (typ) on-capacitance and low  $4.0\Omega$ (typ) on-resistance. In addition, the devices feature a single digital input (CB) to switch between pass-through mode and autodetection charger mode. The USB host charger identification circuit allows a host USB port to support USB chargers with shorted DP/DM detection and to provide support for Apple-compliant devices using a resistor bias on USB data lines. When an Applecompliant device is attached to the port in autodetection charger mode, the devices supply the voltage to the DP and DM lines from the internal resistor-divider. If a USB Revision 1.2-compliant device is attached, the devices short DP and DM to allow correct charger detection. The MAX14566BE features an additional digital input (CB1) to allow forced charger mode.

These devices have enhanced, high electrostatic discharge (ESD) protection on the DP and DM inputs up to  $\pm 15 \text{kV}$  Human Body Model (HBM). All the devices are available in an 8-pin (2mm x 2mm) TDFN package, and are specified over the -40°C to +85°C extended temperature range.

#### **Features**

- ♦ Hi-Speed USB Switching
- ◆ Low 4.0pF (typ) On-Capacitance
- ♦ Low 4.0Ω (typ) On-Resistance
- ♦ Ultra-Low 0.1Ω (typ) On-Resistance Flatness
- ♦ +2.8V to +5.5V Supply Range
- ◆ Ultra-Low 3µA (typ) Supply Current
- Automatic Current-Limit Switch Control
- Automatic USB Charger Identification Circuit
- ♦ ±15kV High ESD HBM Protection On DP/DM
- ♦ 2mm x 2mm, 8-Pin TDFN Package
- ♦ -40°C to +85°C Operating Temperature Range

### **Applications**

Laptops

Netbooks

Universal Charger including iPod®/iPhone® Chargers

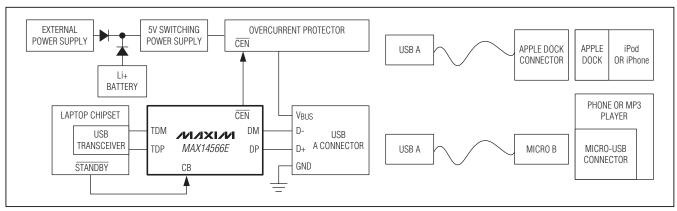
## \_Ordering Information/ Selector Guide

PART	PIN- PACKAGE	CLS CONTROL	TOP MARK
MAX14566EETA+	8 TDFN-EP*	CEN	ADJ
MAX14566AEETA+	8 TDFN-EP*	CEN	ADK
MAX14566BEETA+	8 TDFN-EP*	_	BMR

**Note:** All devices are specified over the -40°C to +85°C operating temperature range.

+Denotes a lead(Pb)-free/RoHS-compliant package.

## **Typical Operating Circuit**



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Maxim Integrated Products 1

<sup>\*</sup>EP = Exposed pad.

#### **ABSOLUTE MAXIMUM RATINGS**

(All voltages referenced to GND.)
VCC, TDP, TDM, CB, DP, DM, CEN/CEN, CB10.3V to +6.0V
Continuous Current into any Terminal ±30mA
Continuous Power Dissipation (T <sub>A</sub> = +70°C)
TDFN (derate 11.9mW/°C above +70°C)954mW

Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Soldering Temperature (reflow)	+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### PACKAGE THERMAL CHARACTERISTICS (Note 1)

TDFN

Junction-to-Ambient Thermal Resistance (θJA)......84°C/W Junction-to-Case Thermal Resistance (θJC)......37°C/W

**Note 1:** Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to <a href="https://www.maxim-ic.com/thermal-tutorial">www.maxim-ic.com/thermal-tutorial</a>.

#### **ELECTRICAL CHARACTERISTICS**

(VCC = 2.8V to 5.5V, TA = TMIN to TMAX, unless otherwise noted. Typical values are at VCC = 5.0V, TA = +25°C.) (Note 2)

PARAMETER	SYMBOL	CON	MIN	TYP	MAX	UNITS	
POWER SUPPLY (MAX14566	SE/MAX14566AE)					-	
Power Cupply Pange	Voc	V <sub>CB</sub> > V <sub>I</sub> H		2.8		5.5	V
Power-Supply Range	Vcc	VCB = 0V (Note 3)		4.75		5.25	V
		VCB = VCC	$V_{CC} = 3.3V$			2	
Supply Current	lcc	VCB - VCC	VCC = 5.5V			7	μΑ
Supply Current	100	VCB = 0V	$V_{CC} = 4.75V$		110	200	]
		VCB = UV	Vcc = 5.25V		120	200	
Supply Current Increase	ΔICC	0 ≤ VCB ≤ VIL or VI	IH ≤ VCB ≤ VCC			2	μΑ
POWER SUPPLY (MAX14566	BBE)						
Power-Supply Range	Vcc	VCB = VCC and VC and VCB1 = 0V or V VCB1 = VCC	B1 = VCC or VCB = VCC VCB = 0V and	2.8		5.5	V
		V <sub>CB</sub> = 0V and V <sub>CB1</sub> = 0V (Note 3)		4.75		5.25	V
		VCB = VCC and VCB1 = VCC or VCB = VCC and VCB1 = 0V	V <sub>CC</sub> = 3.3V			2	- μΑ
Council of Council of	las		V <sub>CC</sub> = 5.5V			7	
Supply Current	ICC	V <sub>CB</sub> = 0V and	V <sub>CC</sub> = 4.75V		110	200	
		VCB1 = 0V	$V_{CC} = 5.25V$		120	200	
		VCB = 0V and VCB1 = VCC	VCC = 5.0V for TYP VCC = 5.5V for MAX		3	7	
Supply Current Increase	Alea	$V_{CB1} = 0V; 0 \le V_{CB} \le V_{IL}$ and $V_{IH} \le V_{CB} \le V_{CC}$ (Note 4)			1		
	Δlcc	$V_{CB} = 0V; 0 \le V_{CB1} \le V_{IL}$ and $V_{IH} \le V_{CB1} \le V_{CC}$ (Note 4)			1		μΑ

### **ELECTRICAL CHARACTERISTICS (continued)**

(VCC = 2.8V to 5.5V, TA = TMIN to TMAX, unless otherwise noted. Typical values are at VCC = 5.0V, TA = +25°C.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
ANALOG SWITCH						
Analog-Signal Range	V <sub>DP</sub> ,V <sub>DM</sub>		0		Vcc	V
On-Resistance TDP/TDM Switch	Ron	VDP = VDM = 0V to VCC, IDP = IDM = 10mA		4.0	6.5	Ω
On-Resistance Match Between Channels TDP/TDM Switch	ΔRON	VCC = 5.0V, VDP = VDM = 400mV, IDP = IDM = 10mA		0.1		Ω
On-Resistance Flatness TDP/ TDM Switch	RFLAT	VCC = 5.0V, $VDP = VDM = 0$ to $VCC$ , $IDP = IDM = 10MA$		0.1		Ω
On-Resistance of DP/DM Short	RSHORT	V <sub>CB</sub> = 0V, V <sub>DP</sub> = 1V, I <sub>DP</sub> = I <sub>DM</sub> = 10mA		40	70	Ω
Off-Leakage Current	ITDPOFF, ITDMOFF	V <sub>CC</sub> = 3.6V, V <sub>DP</sub> = V <sub>DM</sub> = 0.3V to 3.3V, V <sub>TDP</sub> = V <sub>TDM</sub> = 3.3V to 0.3V, V <sub>CB</sub> = 0V	-250		+250	nA
On-Leakage Current	IDPON,IDMON	$V_{CC} = 3.6V$ , $V_{DP} = V_{DM} = 3.3V$ to 0.3V, $V_{CB} = V_{CC}$	-250		+250	nA
DYNAMIC PERFORMANCE						
Turn-On Time	ton	V <sub>TDP</sub> or V <sub>TDM</sub> = 1.5V, R <sub>L</sub> = $300\Omega$ , C <sub>L</sub> = $35pF$ , Figure 1		20	100	μs
Turn-Off Time	toff	V <sub>TDP</sub> or V <sub>TDM</sub> = 1.5V, R <sub>L</sub> = $300\Omega$ , C <sub>L</sub> = $35pF$ , Figure 1		1	5	μs
TDP, TDM Switch Propagation Delay	tPLH, tPHL	$R_L = R_S = 50\Omega$		60		ps
Output Skew	tsk(O)	Skew between DP and DM when connected to TDP and TDM, RL = RS = $50\Omega$ , Figure 2		40		ps
TDP, TDM Off-Capacitance	Coff	f = 1MHz	2.0		рF	
DP, DM On-Capacitance (Connected to TDP, TDM)	Con	f = 240MHz		4.0	5.5	pF
-3dB Bandwidth	BW	$R_L = R_S = 50\Omega$ (Note 4)		1000		MHz
Off-Isolation	VISO	$V_{TDP}$ , $V_{DP}$ = 0dBm, $R_L$ = $R_S$ = $50\Omega$ , $f$ = 250MHz, Figure 3 (Note 4)		-20		dB
Crosstalk	VCT	$V_{TDP}$ , $V_{DP}$ = 0dBm, $R_L$ = $R_S$ = $50\Omega$ , $f$ = 250MHz, Figure 3 (Note 4)		-25		dB
INTERNAL RESISTORS			'			
DP/DM Short Pulldown	R <sub>PD</sub>		335	500	710	kΩ
RP1/RP2 Ratio	RTRP		1.485	1.5	1.515	Ratio
RP1 + RP2 Resistance	R <sub>RP</sub>		95	126	176	kΩ
RM1/RM2 Ratio	RTRM		0.843	0.85	0.865	Ratio
RM1 + RM2 Resistance	R <sub>RM</sub>		70	94	132	kΩ
COMPARATORS						
DM1 Comparator Threshold	V <sub>DM1F</sub>	DM falling	45	46	47	%Vcc
DM1 Comparator Hysteresis				1		%
DM2 Comparator Threshold	V <sub>DM2F</sub>	DM falling	6.31	7	7.6	%Vcc
DM2 Comparator Hysteresis				1		%
DP Comparator Threshold	V <sub>DPR</sub>	DP rising	45	46	47	%Vcc

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{CC} = 2.8V \text{ to } 5.5V, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V_{CC} = 5.0V, T_A = +25^{\circ}C.)$  (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DP Comparator Hysteresis				1		%
LOGIC INPUT (CB, CB1)						
CB/CB1 Input Logic-High	VIH		1.4			V
CB/CB1 Input Logic-Low	VIL				0.4	V
CB/CB1 Input Leakage Current	IIN	$V_{CC} = 5.5V$ , $0V \le V_{CB} \le V_{IL}$ or $V_{IH} \le V_{CB} \le V_{CC}$	-1		+1	μA
CEN/CEN OUTPUTS						
V <sub>BUS</sub> Toggle Time (MAX14566E/ MAX14566AE)	tvBT	CB = logic 0 to logic 1 or logic 1 to logic 0	0.5	1	2	S
CEN Output Logic-High Voltage		CB = logic 0 to logic 1, ISOURCE = 2mA (MAX14566E only)	V <sub>C</sub> C - 0.4			V
CEN Output Leakage Current		V <sub>CC</sub> = 5.5V, V <sub>CEN</sub> = 0V, <del>CEN</del> deasserted (MAX14566E only)			1	μΑ
CEN Output Logic-Low Voltage		CB = logic 0 to logic 1, I <sub>SINK</sub> = 2mA (MAX14566AE only)			0.4	V
CEN Output Leakage Current		VCC = VCEN = 5.5V, CEN deasserted (MAX14566AE only)			1	μA
ESD PROTECTION						
ESD Protection Level (DP and DM Only)	VESD	НВМ		±15		kV
ESD Protection Level (All Other Pins)	VESD	НВМ		±2		kV

- Note 2: All units are 100% production tested at  $T_A = +25$ °C. Specifications over temperature are guaranteed by design.
- **Note 3:** The part is operational from +2.8V to +5.5V. However, in order to have the valid Apple resistor-divider network, the VCC supply must stay within the range of +4.75V to +5.25V.
- Note 4: Guaranteed by design.

## Test Circuits/Timing Diagrams

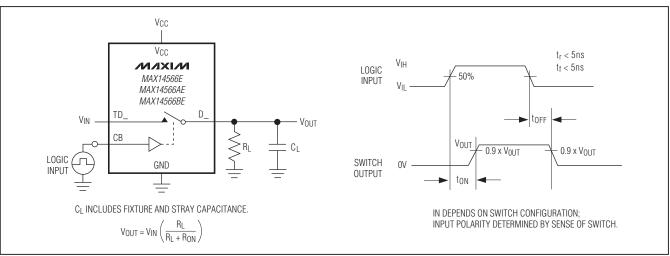


Figure 1. Switching Time

## Test Circuits/Timing Diagrams (continued)

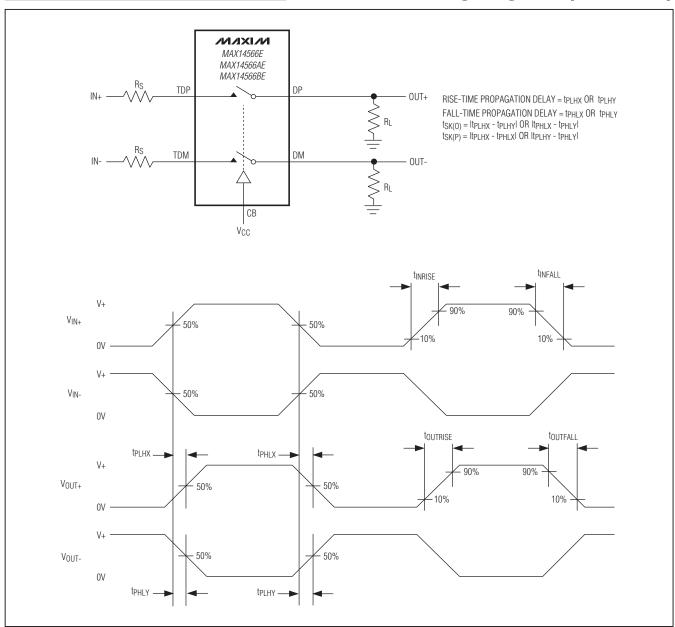


Figure 2. Output Signal Skew

### **Test Circuits/Timing Diagrams (continued)**

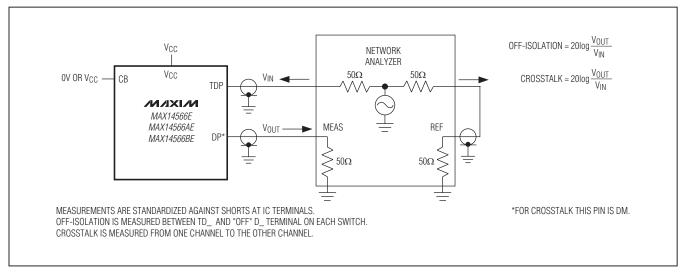
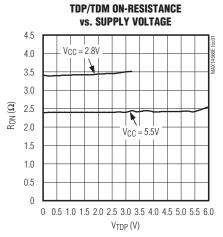
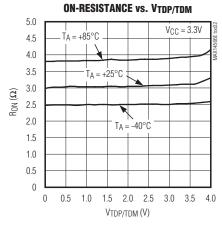


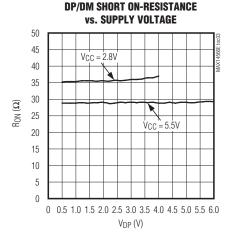
Figure 3. Off-Isolation and Crosstalk

## Typical Operating Characteristics

(VCC = 5V, TA = +25°C, unless otherwise noted.)



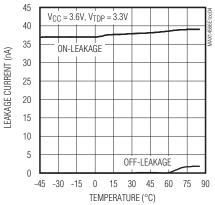




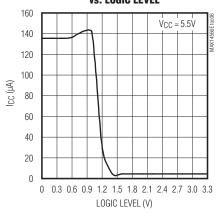
## \_Typical Operating Characteristics (continued)

(VCC = 5V, TA = +25°C, unless otherwise noted.)

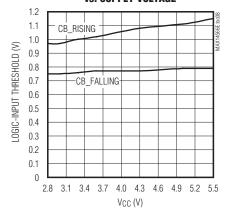
# TDP/DP LEAKAGE CURRENT vs. Temperature



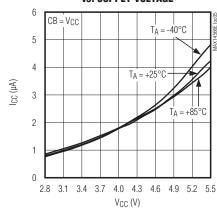
# SUPPLY CURRENT vs. LOGIC LEVEL



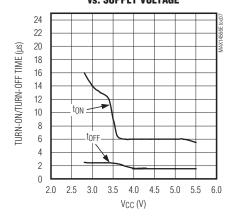
# LOGIC-INPUT THRESHOLD vs. SUPPLY VOLTAGE



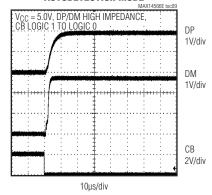
# SUPPLY CURRENT vs. SUPPLY VOLTAGE



## TURN-ON/TURN-OFF TIME vs. SUPPLY VOLTAGE



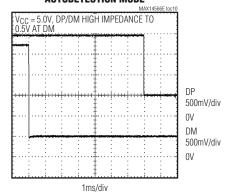
#### **AUTODETECTION MODE**



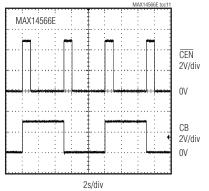
**Typical Operating Characteristics (continued)** 

(V<sub>CC</sub> = 5V,  $T_A$  = +25°C, unless otherwise noted.)

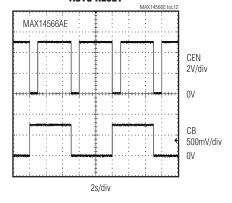
#### **AUTODETECTION MODE**



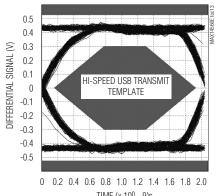
#### **AUTO RESET**



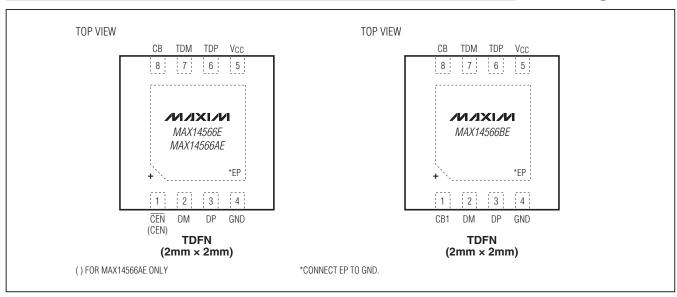
#### **AUTO RESET**



#### **USB EYE DIAGRAM**



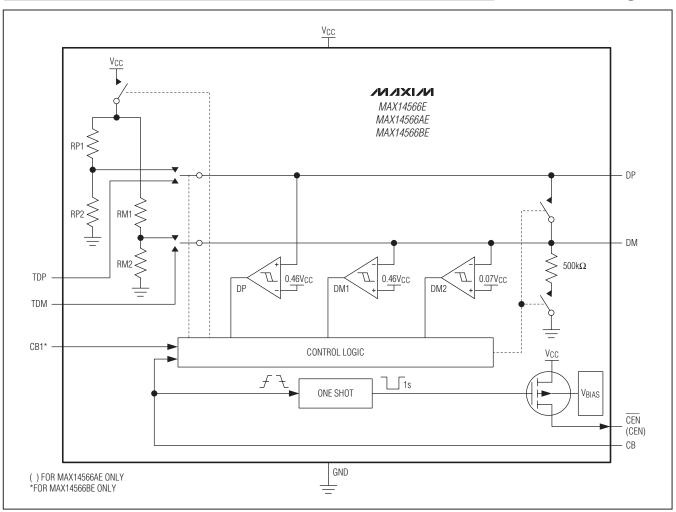
## Pin Configuration



## **Pin Description**

	PIN		NAME	FUNCTION	
MAX14566E	MAX14566AE	MAX14566BE	IVAIVIE	FUNCTION	
_	1	_	CEN	nMOSFET Open-Drain Output, Current-Limit Switch (CLS) Control Output. If CB changes from logic 0 to logic 1 or from logic 1 to logic 0, CEN is low for 1s (typ).	
1	_	_	CEN	Active-Low pMOSFET Open-Drain Output, Current-Limit Switch (CLS) Control Output. If CB changes from logic 0 to logic 1 or logic 1 to logic 0, $\overline{\text{CEN}}$ is high for 1s (typ).	
_	_	1	CB1	Switch Control Bit. See Table 2.	
2	2	2	DM	USB Connector D- Connection	
3	3	3	DP	USB Connector D+ Connection	
4	4	4	GND	Ground	
5	5	5	Vcc	Power Supply. Connect a 0.1µF capacitor between VCC and GND as close as possible to the device.	
6	6	6	TDP	Host USB Transceiver D+ Connection	
7	7	7	TDM	Host USB Transceiver D- Connection	
8	8	8	СВ	Switch Control Bit. See Table 1. CB = logic 0, charger mode CB = logic 1 (PM), pass-through mode active, DP/DM connected to TDP/TDM	
_	_	_	EP	Exposed Pad. Connect EP to ground. Do not use EP as the only ground connection.	

### **Functional Diagram**



### **Detailed Description**

The MAX14566E/MAX14566AE/MAX14566BE are Hi-Speed USB analog switches that support USB hosts to identify the USB port as a charger port when the USB host is in a low-power mode and cannot enumerate USB devices. These devices feature high-performance Hi-Speed USB switches with low 4pF (typ) on-capacitance and low  $4\Omega$  (typ) on-resistance. DP and DM can handle signals between 0V and 6V with any supply voltage.

#### **Resistor-Dividers**

All the devices feature an internal resistor-divider for biasing data lines to provide support for Apple-compliant devices. When these devices are not operated with the resistor-divider, they disconnect the resistor-dividers from the supply voltage to minimize supply current requirements. The resistor-dividers are not connected in pass-through mode.

#### **Switch Control**

The MAX14566E/MAX14566AE feature a single digital input, CB, for mode selection (Table 1). Connect CB to a logic-level low voltage for autodetection charger mode (AM). See the *Autodetection* section for more information. Connect CB to a logic-level high voltage for normal high-speed pass-through mode (PM). The MAX14566BE features dual digital inputs, CB and CB1, for mode selection (Table 2). Connect CB to a logic-level high for normal high-speed pass-through mode (PM). Connect CB to a logic-level low for different charger-mode selection

with CB1. Connect CB1 to a logic-level low for auto mode (AM) or connect CB1 to a logic-level high for forced dedicated-charger mode (FM).

#### **Autodetection**

All the devices feature autodetection charger mode for dedicated chargers and USB masters. CB must be set low to activate autodetection charger mode.

In autodetection charger mode, the MAX14566E monitors the voltages at DM and DP to determine the type of the device attached. If the voltage at DM is +2.3V (typ) or higher and the voltage at DP is +2.3V (typ) or lower, the voltage stays unchanged.

If the voltage at DM is forced below the +2.3V (typ) threshold, the internal switch disconnects DM and DP

from the resistor-divider and DP and DM are shorted together for dedicated charging mode.

If the voltage at DP is forced higher than the +2.3V (typ) threshold, the internal switch disconnects DM and DP from the resistor-divider and DP and DM are shorted together for dedicated charging mode.

Once the charging voltage is removed, the short between DP and DM is disconnected for normal operation.

#### **Automatic Peripheral Reset**

The MAX14566E/MAX14566AE feature automatic current-limit switch control output. This feature resets the peripheral connected to VBUS in the event the USB host switches to or from standby mode. CEN/CEN provide a 1s (typ) pulse on the rising or falling edge of CB (Figures 4, 5, and 6).

Table 1. Digital Input State (MAX14566E/MAX14566AE)

СВ	MODE	DP/DM	COMMENT	INTERNAL RESISTOR-DIVIDER
0	AM	Autodetection Circuit Active	Auto Mode	Connected
1	PM	Connected to TDP/TDM	USB Traffic Active	Not Connected

Table 2. Digital Input State (MAX14566BE)

СВ	CB1	MODE	STATUS		
0	0	AM	Auto Mode		
0	1	FM	Forced Dedicated-Charger Mode: DP/DM Shorted		
1	Х	PM	Pass-Through (USB) Mode: Connect DP/DM to TDP/TDM		

X = Don't care.

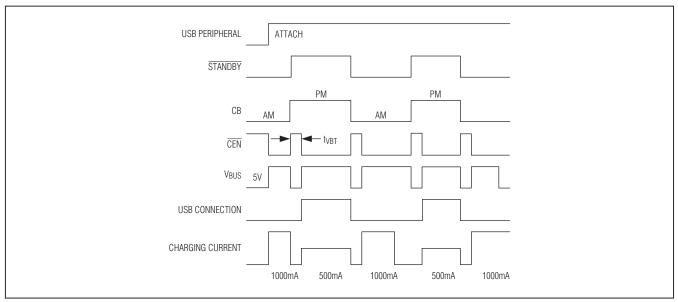


Figure 4. MAX14566E Peripheral Reset Timing Diagram

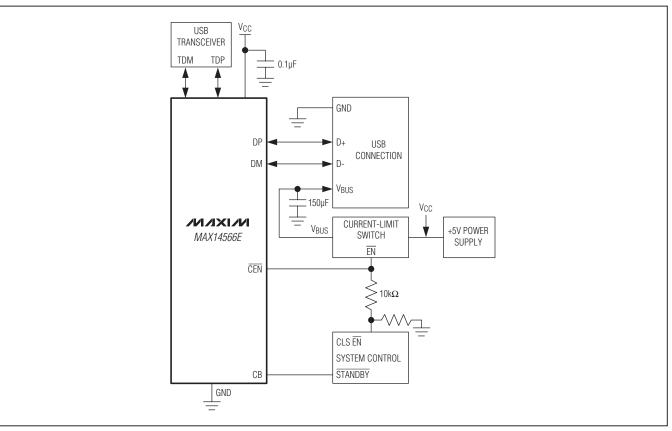


Figure 5. MAX14566E Peripheral Reset Applications Diagram

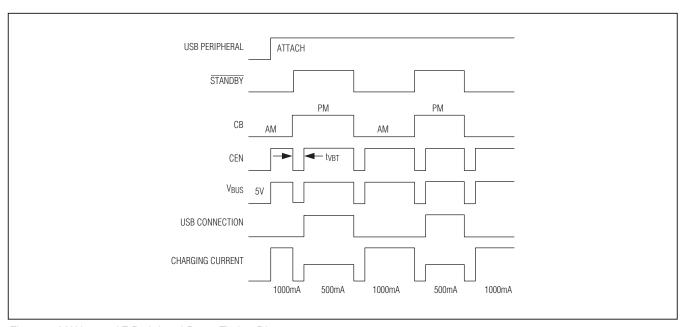


Figure 6. MAX14566AE Peripheral Reset Timing Diagram

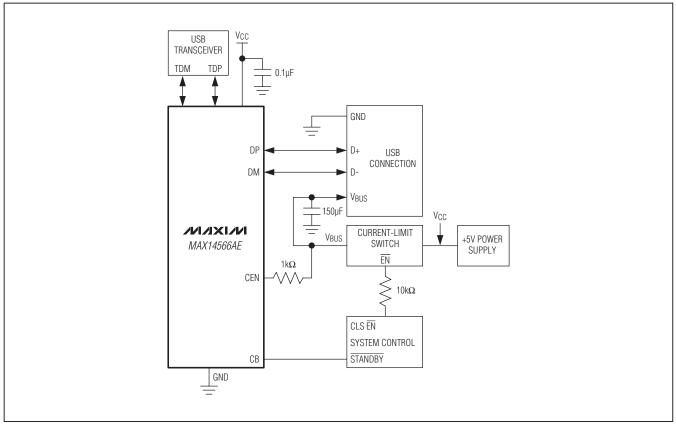


Figure 7. MAX14566AE VBUS Discharge Circuit

#### **Bus Voltage Discharge**

The MAX14566AE automatic current-limit switch control output can be used to discharge the VBUS during VBUS reset. When the system controls the current-limit switch for VBUS toggle, the output capacitor can be discharged slowly depending upon the load. If fast discharge of the VBUS capacitor is desired, the CEN output can be used to achieve the fast discharge as shown in Figure 7.

#### **Data Contact Detect**

All the devices support USB devices that require detecting the USB data lines prior to charging. When a USB Revision 1.2-compliant device is attached, the USB data lines DP and DM are shorted together. The short remains until it is detected by the USB device. This feature guarantees appropriate charger detection if a USB Revision 1.2-compliant device is attached. The autodetection charger mode is activated after the data contact detect

is established. CB must be set low to activate data contact detect.

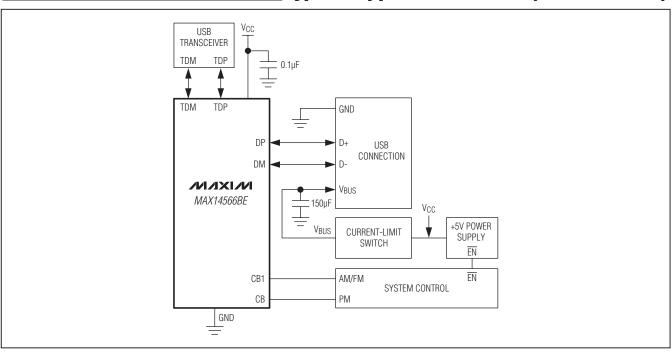
#### **ESD Test Conditions**

ESD performance depends on a variety of conditions. Contact Maxim for a reliability report that documents test setup, test methodology, and test results.

# Extended ESD Protection (Human Body Model)

ESD-protection structures are incorporated on all pins to protect against electrostatic discharges up to ±2kV (HBM) encountered during handling and assembly. DP and DM are further protected against ESD up to ±15kV (HBM) without damage. The ESD structures withstand high ESD both in normal operation and when the device is powered down. After an ESD event, the device continues to function without latchup (Figure 8).

### Typical Application Circuit (MAX14566BE)



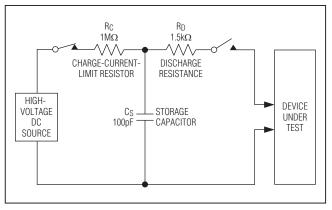


Figure 8a. Human Body ESD Test Model

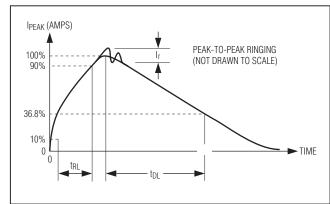


Figure 8b. Human Body Current Waveform

## Chip Information

PROCESS: BiCMOS

### \_Package Information

For the latest package outline information and land patterns (footprints), go to **www.maxim-ic.com/packages**. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE	PACKAGE	OUTLINE	LAND
TYPE	CODE	NO.	PATTERN NO.
8 TDFN-EP	T822+1	21-0168	90-0064

## Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	10/10	Initial release	_
1	3/11	Changed the USB Battery Charging Specification Revision 1.1 to Revision 1.2	1, 13

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